Speaker Bios

Eckart Hoene

Eckart Hoene received the M.Sc. degree in 1997 with a thesis on “Study of drive engineering at TU-Berlin” and the Ph.D. in 2000 on “Predicting EMI behavior of drive systems”. He is with Fraunhofer IZM, Berlin since 1997 and since 2006 he leads a research group of 10 scientist in the field of Packaging and Prototype development for Power Electronics.

Prof. Dr.-Ing. Eckart Hoene is currently Business development manager Power and in 2014 he has become Adjunct Professor at Aalborg University.

Dr. -Ing. Eckart Hoene holds 5 international patents in his field of interest.

Garron Morris

Garron Morris has over 24 years of experience in reliability and thermal management of IGBTs used in Rockwell Automation motor drives and GE Healthcare MRI medical imaging systems. As a Principal Engineer in the Rockwell Automation in the motor drives research and development group, he is currently focused on developing the next generation of reliable motor drives, implementing advanced predictive life models, and solving corrosion issues in power electronics. He has Bachelors and Masters degrees in Mechanical Engineering from University of Wisconsin at Milwaukee in the United States. Garron has authored over 30 conference and journal publications and has 15 US patents.

Cyril Buttay

Cyril Buttay received the Engineer and Ph.D. degrees from the Institut National des Sciences Appliquées (INSA) Lyon, Lyon, France, in 2001 and 2004, respectively.

From 2005 to 2007, he was a Research Associate with the Electrical Machines and Drives Research Team, University of Sheffield, Sheffield, U.K., and the Power Electronics Machines and Control Group, University of Nottingham, Nottingham, U.K.

Since 2008, he has been a Scientist with the French Centre National de Recherche Scientifique (CNRS), where he was with the Ampére Laboratory, Lyon, on the topic of packaging for power electronics, with a special focus on high-temperature, high-voltage, or highdensity applications. In 2020 he was a Visiting Scholar with the Center for Power Electronics Systems (CPES), Virginia Tech, Blacksburg, VA, USA.

Nick Baker

Nick Baker received the M.Eng. degree in electrical and electronic engineering from Loughborough University, Leicestershire, U.K., in 2011. He completed his PhD in 2016 at Aalborg University on Junction Temperature Measurements in Power Semiconductors. In 2015, he was awarded European Power Electronics Association Young Member Award. From 2017 to 2019 he was a Post-Doc at Aalborg University, and has been an Independent Researcher funded by the Danish Independent Research Fund since 2020. His research interests are temperature measurements in power modules, intelligent power modules and

Ty McNutt

Dr. Ty McNutt currently serves as Director of Business Development for the Fayetteville, Arkansas location of Wolfspeed, a Cree Company. He manages various technical projects, and works closely

with customers and their applications teams to integrate advanced silicon carbide device and packaging technologies into next generation systems. He is an inventor on seven issued patents on silicon carbide materials, devices, packaging, and applications, as well as authored or co-authored over 70 publications on wide bandgap devices. Dr. McNutt has been working in the field of silicon carbide for over 18 years and received his Ph.D. in Electrical Engineering from the University of Arkansas in the field of silicon carbide semiconductor device physics.

Patrick McCluskey

Dr. Patrick McCluskey is a Professor of Mechanical Engineering at the University of Maryland, College Park. Dr. McCluskey conducts research in the Center for Advanced Life Cycle Engineering (CALCE) focusing in the areas of thermal management, reliability, and packaging of electronic systems for use in extreme temperature environments and high power applications. He has authored or co-authored over 100 technical articles and 3 books, including “High Temperature Electronics.” He has served as technical chairman of the IMAPS International High Temperature Electronic Conference and Exhibition (HiTEC) and is on the organizing committee for the International High Temperature Electronics Network Conference (HiTEN). He is an associate editor of the IEEE Transactions on Components and Packaging. He is a fellow of the International Microelectronics and Packaging Society (IMAPS), and is a member of ASME, IEEE, and SAE.

Stephane Azzopardi

TBC

Mona Ghassemi

TBC

Nicolas Botter

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